

Technical Data Copper, pure and low-alloyed ¹⁾

		Copper	Oxygen-free Copper		Copper alloyed		
		Cu-ETP1	Cu-OF1	Cu-OF1 selekt. ^{*)}	CuAg0,1 ^{*)}	HCHS ^{**)}	
Material - No.	DIN / EN	CW003A	CW007A	-	CW013A	-	
	UNS	C11040	C10100	-	C11600	-	
Nominal Composition	[%]	≥ 99,95 Cu	≥ 99,99 Cu	≥ 99,99 Cu Incl. Ag	≥ 99,80 Cu Ag 0,1	≥ 99,60 Cu	
Conductivity ²⁾	[m/(Ohm mm ²)]	58	58	58	57	50	
Conductivity ²⁾	[% IACS]	100	100	100	98	86	
Thermal Conductivity ²⁾	[W/(m K)]	390	390	390	390	355	
Coefficient of Thermal Expansion ³⁾	[10 ⁻⁶ / K]	17	17	17	17	17	
Tensile Strength annealed	[N/mm ²]	240	240	240	240	-	
Elongation annealed	[%]	30	30	30	30	-	
Tensile Strength hard	[N/mm ²]	450	450	450	450	600	
Density	[g/cm ³]	8,9	8,9	8,9	8,9	8,9	

1) Nominal data for diameter 0,8 mm

2) At 20° C

3) Temperature range 20 - 200° C

*) higher thermal resistance

***) excellent thermal resistance up to 600° C (**H**igh **C**onductivity **H**igh **S**trength)